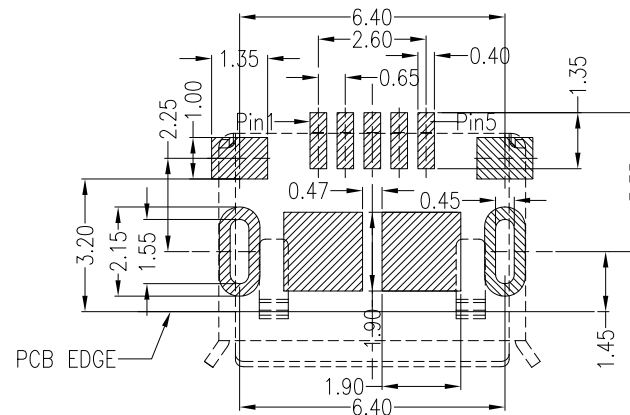
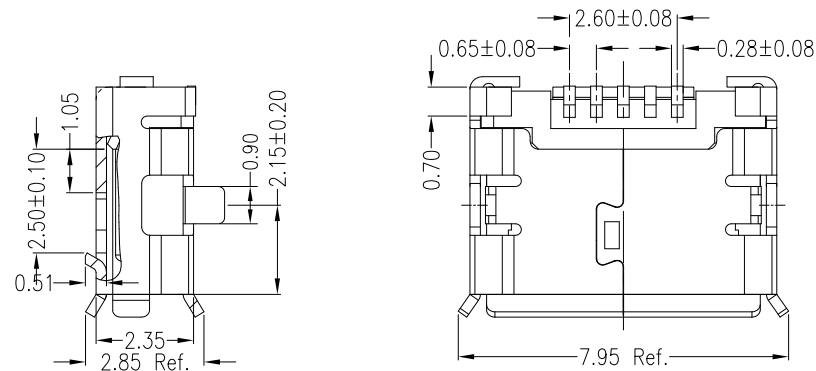
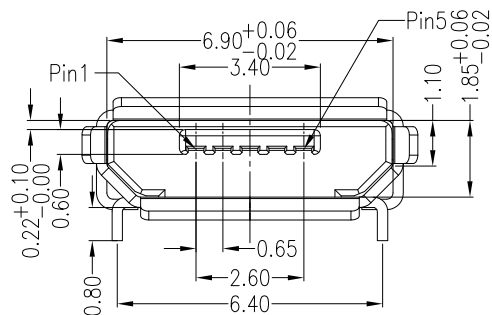
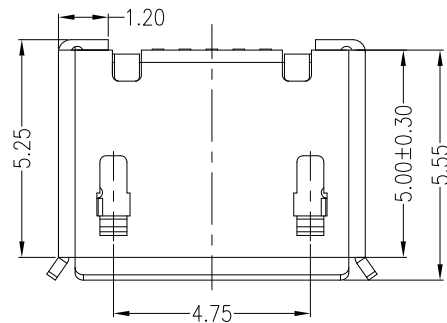
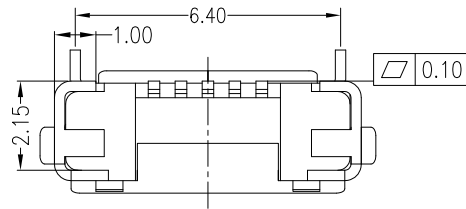
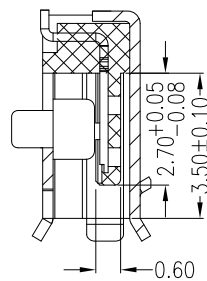


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2017/11/23	Phebe Su
A1			Modify material	2017/11/23	Phebe Su



RECOMMENDED PCB LAYOUT

PCB图仅供参考

Note:

1.Material:

- 1.1 Housing: High temperature thermoplastic with g.f, UL94V-0, LCP BLACK.
- 1.2 Contact: Copper Alloy, $t=0.20\text{mm}$, Gold Flash plated over nickel underplating overall.
- 1.3 Shell: SUS304, Nickel plated overall.

2.Specification:

- 2.1 Current rating: 1.5PIN 1.8A Max/2,3,4PIN 1A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 30 m Ω Max.
- 2.4 Insulation resistance: 100 M Ω Min.
- 2.5 Total mating force: 3.57 Kg Max.
- 2.6 Total unmating force: 1.0 Kg Min.
- 2.7 Temperature range: $-40^{\circ}\text{C}\sim 85^{\circ}\text{C}$
- 2.8 Durability: 10000 Cycles

MATRIX PART NO:

MUSB 05 - 01 - 279

MATRIX USB Pin Number Series number Plating 01:Gold Flash



Matrix Electronics Co.,Ltd

TOLERANCE: X.X ± 0.15 X.XX ± 0.10 X.XXX ± 0.05 ANGLE: $\pm 3^{\circ}$	DESIGN BY : Phebe Su	DATE : 2017/11/23	PART NAME: Micro usb 5S B Type SMT	
	CHECKED BY: Vicky Hsieh	DATE : 2017/11/23	PART NO.	MUSB05-01-279
 UNIT: mm [inch] SCALE:1:1 SIZE:A4	APPROVED BY1: Richard Hsieh	DATE : 2017/11/23	MOLD NO.	NA
	APPROVED BY2: Richard Hsieh	DATE : 2017/11/23	DRAW NO.	
			SHEET NO.	1 OF 1